



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0406-04** DATE: July 15, 2004
Product Affected: IDT 74SSTV16857

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark
- Date Code
- Other

Date Effective: July 15, 2004

Contact: Bimla Paul
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Attachment: Yes No

Samples: Available upon request.

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology To provide improved Tpd timing parameter.
- Wafer Fabrication Process There is no change in die technology/process.
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

RELIABILITY/QUALIFICATION SUMMARY:

Not Applicable. This is a data sheet change only

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ***Approval for shipments prior to effective date.***
Name/Date: _____ E-Mail Address: _____
Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT - PCN #: L0406-04

PCN Type: Data Sheet

Data Sheet Change: Yes

Detail of Change: Revise Tpd timing parameter

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URL: http://www1.idt.com/pcms/tempDocs/74SSTV16857_datasheet.pdf

Symbol	Parameter	From	To
Tpd	CLK and CLK\ to Q	1.1 nsec Min, 2.8 nsec Max	1.1 nsec Min, 2.4 nsec Max